High Voltage Transistor

PNP Silicon

Features

- AEC-Q101 Qualified and PPAP Capable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V _{CEO}	-150	Vdc
Collector – Base Voltage	V _{CBO}	-160	Vdc
Emitter-Base Voltage	V _{EBO}	-5.0	Vdc
Collector Current – Continuous	Ι _C	-500	mAdc

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit	
Total Device Dissipation FR-5 Board (Note 1) $T_A = 25^{\circ}C$	P _D	225	mW	
Derate Above 25°C		1.8	mW/°C	
Thermal Resistance, Junction-to-Ambient	$R_{ hetaJA}$	556	°C/W	
Total Device Dissipation Alumina Substrate (Note 2) $T_A = 25^{\circ}C$	PD	300	mW	
Derate Above 25°C		2.4	mW/°C	
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W	
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C	

1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.

2. Alumina = 0.4 \times 0.3 \times 0.024 in 99.5% alumina.

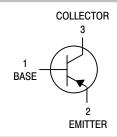


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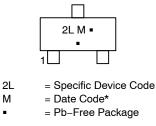
http://onsemi.com



SOT-23 (TO-236) CASE 318 STYLE 6



MARKING DIAGRAM



(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
MMBT5401LT1G	SOT-23 (Pb-Free)	3,000 Tape & Reel
SMMBT5401LT1G	SOT-23 (Pb-Free)	3,000 Tape & Reel
MMBT5401LT3G	SOT-23 (Pb-Free)	10,000 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector – Emitter Breakdown Voltage $(I_C = -1.0 \text{ mAdc}, I_B = 0)$	V _{(BR)CEO}	-150	_	Vdc
Collector – Base Breakdown Voltage $(I_C = -100 \ \mu Adc, I_E = 0)$	V _{(BR)CBO}	-160	_	Vdc
Emitter – Base Breakdown Voltage $(I_E = -10 \ \mu Adc, \ I_C = 0)$	V _{(BR)EBO}	-5.0	_	Vdc
Collector–Base Cutoff Current $(V_{CB} = -120 \text{ Vdc}, I_E = 0)$ $(V_{CB} = -120 \text{ Vdc}, I_E = 0, T_A = 100^{\circ}\text{C})$	I _{CBO}	-	-50 -50	nAdc µAdc
ON CHARACTERISTICS				
DC Current Gain ($I_C = -1.0 \text{ mAdc}, V_{CE} = -5.0 \text{ Vdc}$) ($I_C = -10 \text{ mAdc}, V_{CE} = -5.0 \text{ Vdc}$) ($I_C = -50 \text{ mAdc}, V_{CE} = -5.0 \text{ Vdc}$)	h _{FE}	50 60 50	_ 240 _	_
Collector – Emitter Saturation Voltage ($I_C = -10$ mAdc, $I_B = -1.0$ mAdc) ($I_C = -50$ mAdc, $I_B = -5.0$ mAdc)	V _{CE(sat)}	-	-0.2 -0.5	Vdc
Base – Emitter Saturation Voltage ($I_C = -10 \text{ mAdc}, I_B = -1.0 \text{ mAdc}$) ($I_C = -50 \text{ mAdc}, I_B = -5.0 \text{ mAdc}$)	V _{BE(sat)}	-	-1.0 -1.0	Vdc
SMALL-SIGNAL CHARACTERISTICS				
Current – Gain — Bandwidth Product ($I_C = -10$ mAdc, $V_{CE} = -10$ Vdc, f = 100 MHz)	f _T	100	300	MHz
Output Capacitance $(V_{CB} = -10 \text{ Vdc}, I_E = 0, f = 1.0 \text{ MHz})$	C _{obo}	_	6.0	pF
Small Signal Current Gain (I _C = -1.0 mAdc, V _{CE} = -10 Vdc, f = 1.0 kHz)	h _{fe}	40	200	-
	NF			dB

8.0

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Noise Figure (I_C = -200 μ Adc, V_{CE} = -5.0 Vdc, R_S = 10 Ω , f = 1.0 kHz)

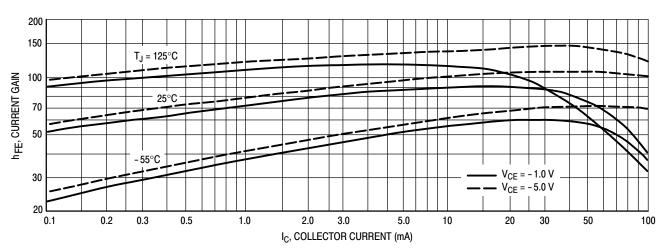
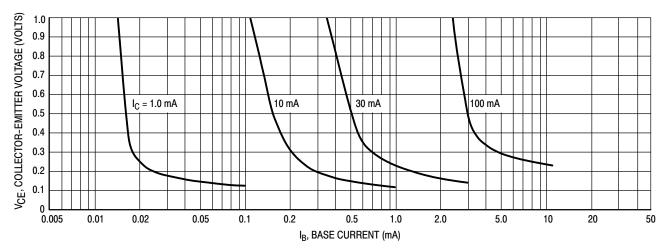
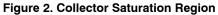


Figure 1. DC Current Gain





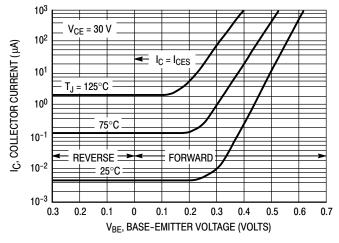
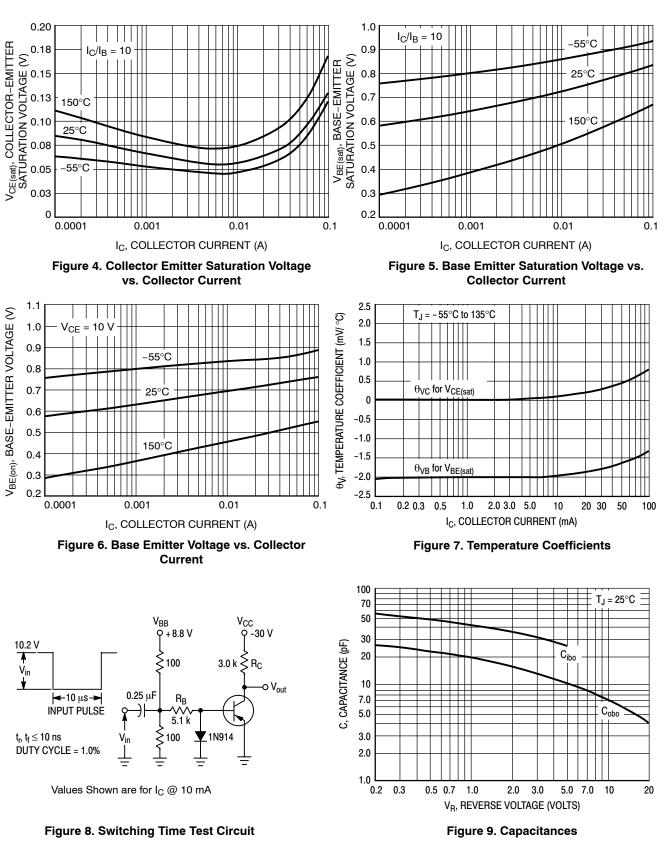
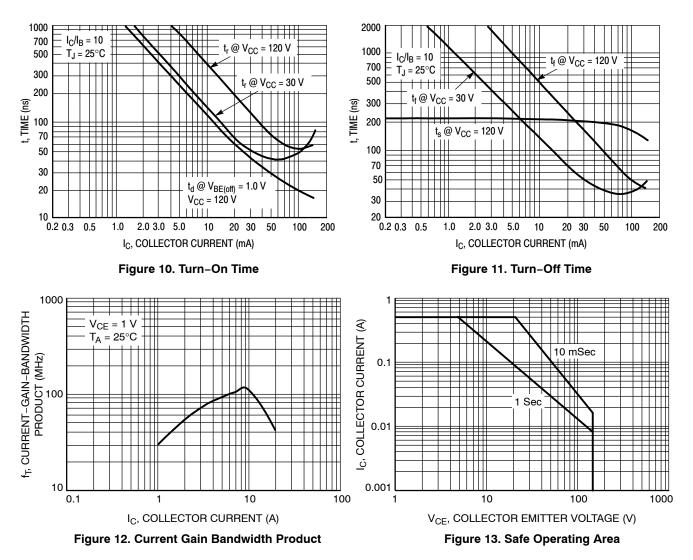


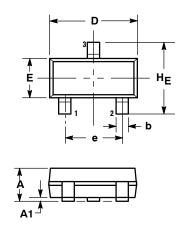
Figure 3. Collector Cut-Off Region

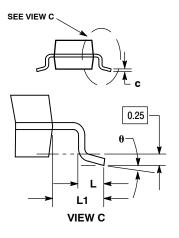




PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AP**





NOTES

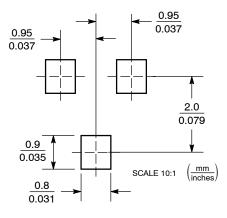
- DIBENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM
- THICKNESS OF BASE MATERIAL. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,
- 4. PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104
θ	0°		10°	0°		10°

STYLE 6: PIN 1. 2. BASE

EMITTER 3. COLLECTOR

SOLDERING FOOTPRINT



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